

Amendments to the Abstract:

Please replace the Abstract beginning at line 5, page 25 with the following rewritten paragraph:

ABSTRACT

A method of forming a microelectronic structure and its associated structures is described. In one embodiment, ~~That method comprises providing~~ a substrate is provided ~~comprising with~~ a sacrificial layer disposed on a hard mask layer, and a metal layer disposed in a trench of the substrate and on the sacrificial layer, ~~removing the~~ The metal layer is then removed at a first removal rate wherein a dishing is induced on a top surface of the metal layer until the sacrificial layer is exposed, and simultaneously removing the metal layer and the sacrificial layer at a second removal rate without substantially removing the hard mask.